

SONY**CXP5070****CMOS 4-bit 1 Chip Microcomputer**

Piggyback type

Description

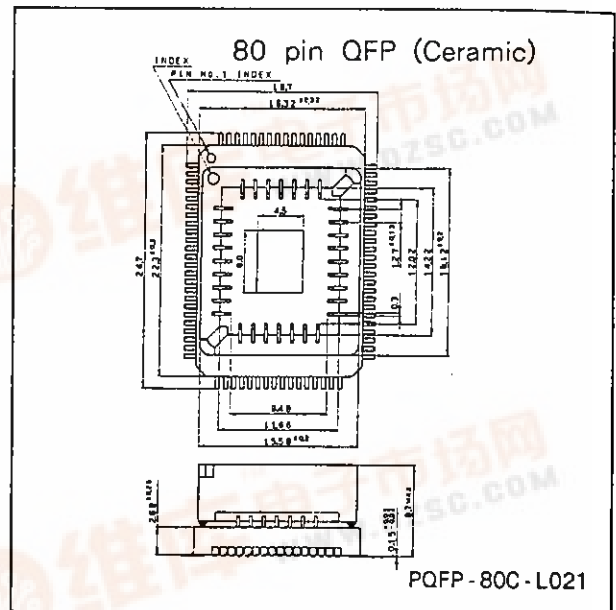
CXP5070 is a CMOS 4-bit 1 chip microcomputer of piggyback/evaluator combined type which has been developed for functional evaluation of the CXP5076/CXP5078.

Features

- Instruction cycle 1.9 μ s/4.19MHz
122 μ s/32kHz
(Possible to select with the program)
- ROM capacity Maximum 8K bytes
(EPROM 27C64 LCC)
- RAM capacity 448 \times 4 bits
(Including stack area)
(32 \times 4 bits is used in combination with the LCD display memory.)
- 43 general purpose I/O ports
(When the combined pins specify the ports)
- LCD controller/driver (Possible to direct drive)
 - Possible to select with the program the segment output of 16 to 32
 - Possible to select with the program the duty of static, 1/2, 1/3 and 1/4
 - Possible to select with the program the bias of 1/2 and 1/3
- 14-bit PWM output for D/A conversion
- Remote control receiving circuit
- 3-bit A/D converter (8 channels per circuit)
- 32kHz timer/event counter
- Power supply voltage detection reset function
- Low voltage operation (2.5V)when operating in 122 μ s/32kHz
- 8 high current output port
- Rich wake-up function
- 8-bit/4-bit variable serial I/O
- 8-bit timer, 8-bit timer/event counter and 18-bit time base timer, independently controlled
- 2 kinds of power down modes of sleep and stop
- Power on reset circuit (mask option)
- Provided with 80 pin piggyback QFP

Package Outline

Unit : mm

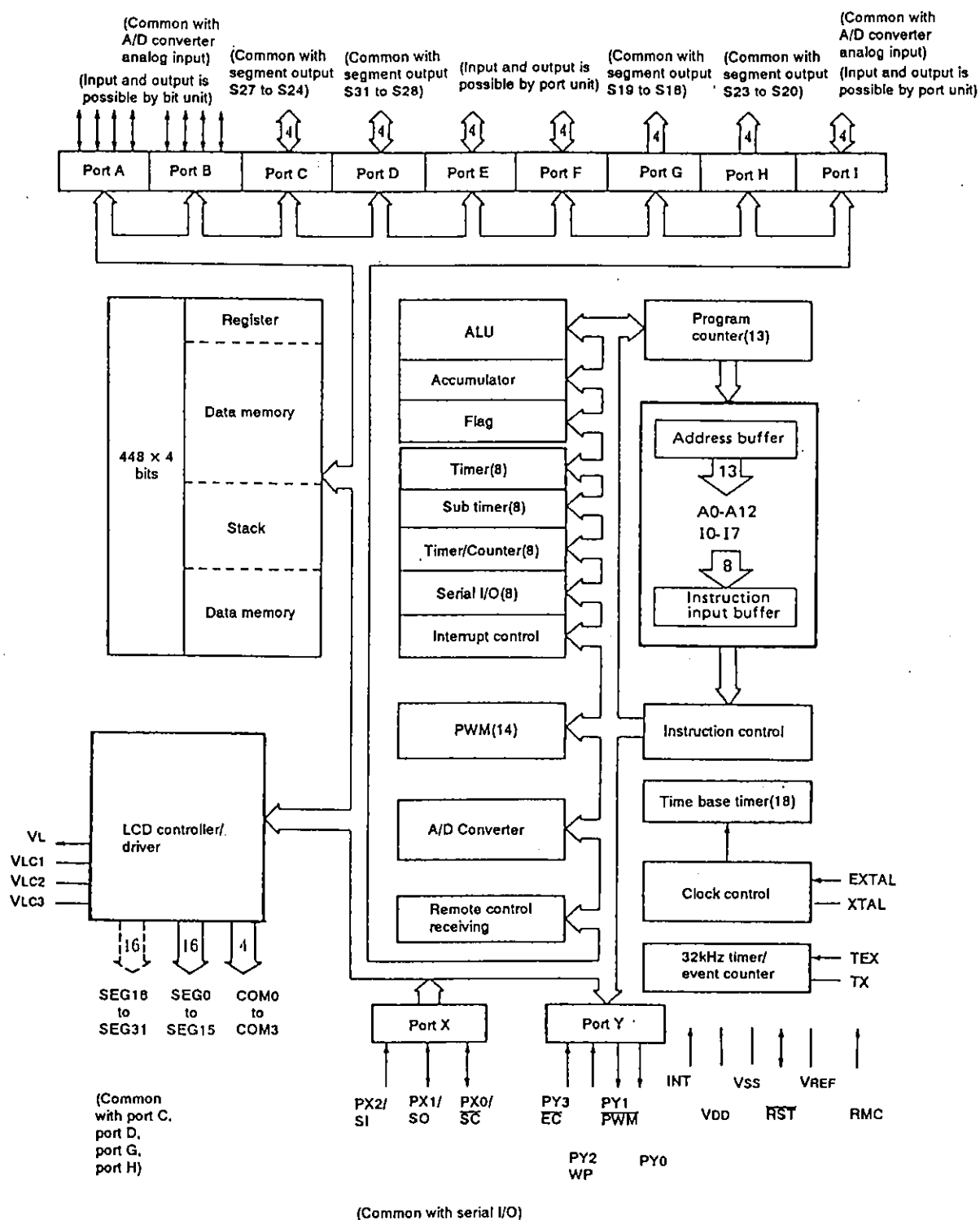


Note) Mask options are determined according to the CXP5070 category.
For details refer to the product list.

Structure

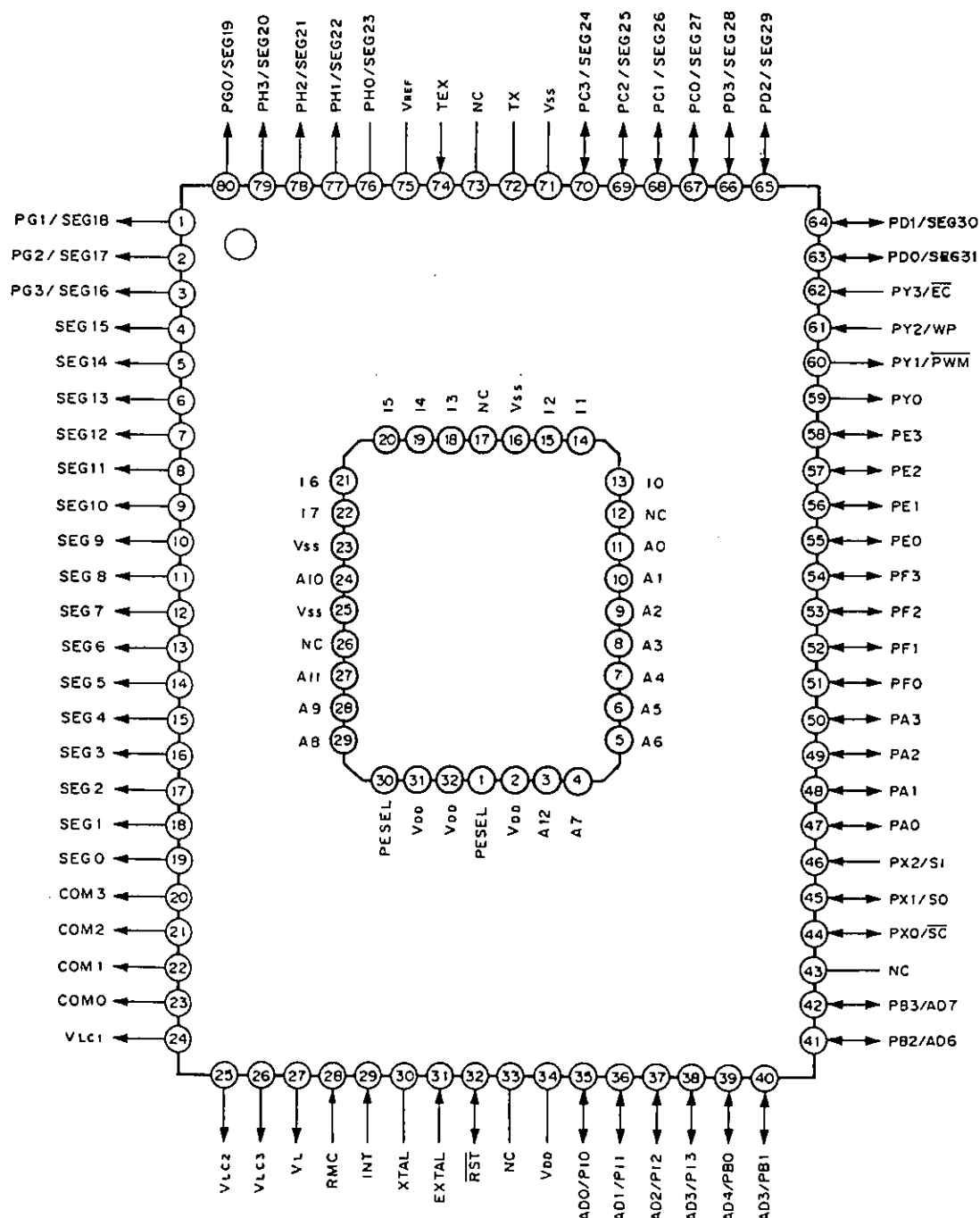
Silicon gate CMOS IC

Block Diagram

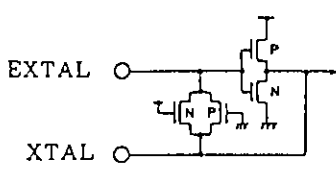
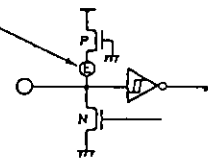

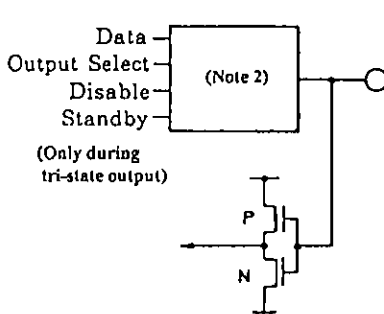


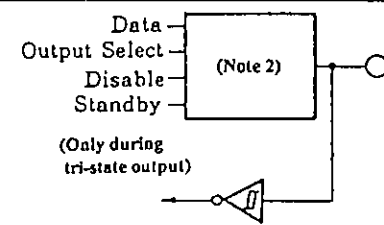

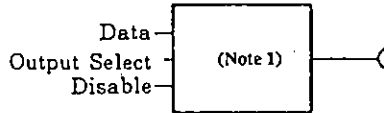
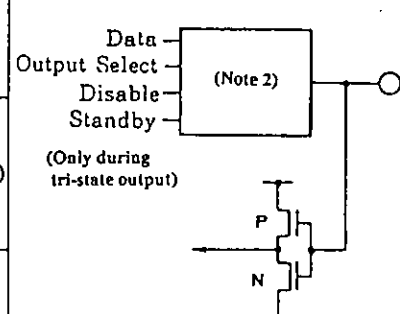
Pin Configuration Diagram (Top View)

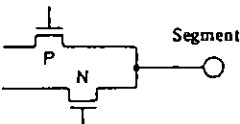
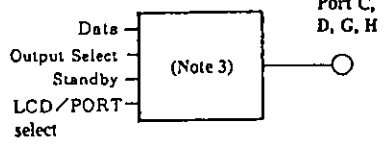
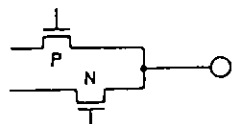
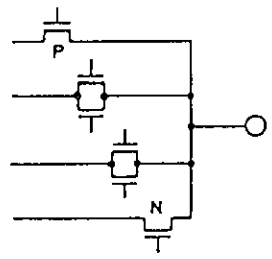
- Note** 1) PESEL pin serves to switch the I/O signal of the socket on top of the package from interface with the evaluator (Eva mode) to interface with EPROM (Piggyback mode). Setting PESEL pin to H level brings Eva mode to enable the connection with the evaluator. Setting it to L level brings piggy mode to enable the mounting of EPROM. For EVA, CAP-2 this switching is executed on the evaluator side. All there is to change is the plugging of EVACAP and EPROM otherwise no special measure is required.
- 2) Do not make any connections to NC pins.

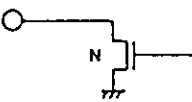

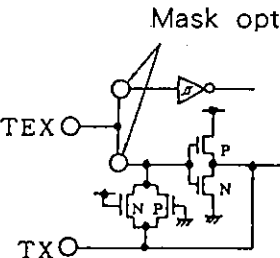


Pin Description

Symbol	Name	I/O	Equivalent Circuit	Description
V _{DD}	Supply voltage	—		Positive voltage supply pin
V _{SS}	Grounding voltage	—		GND pin
EXTAL	Clock input	I		Clock oscillation circuit input pin. Connect the crystal oscillator or ceramic resonator between the EXTAL and XTAL. To use an external clock input, connect the clock oscillation source to the EXTAL pin and open the XTAL pin.
XTAL	Clock output	O		Clock oscillation circuit output pin
$\overline{\text{RST}}$	Reset	I/O	<p>Mask option</p>  <p>Output pull-up resistor (P-ch Tr) N-ch Tr output Schmitt inverter input</p>	Serves as the incorporated power-on reset circuit output pin. When inputting a reset signal from the outside, provide 2 instruction cycles or longer of an "L" level (0V).
INT	External interrupt	I		Serves as interrupt input pin. Permits the selection with a program of the edge and the level modes.
RMC	Remote control input	I		Remote control receiver input pin
PX2/SI	Port X Serial input	I	Schmitt inverter input	Doubles as a serial interface (8 bits) input pin and as bit "2" (input) of port X.
PX1/SO	Port X Serial output	I/O	 <p>See Note 2) for the output circuit format. Inverter input</p>	Doubles as a serial interface (8 bits) output pin and as bit "1" (input) of port X. (SO output possible to inhibit with the program.)

Symbol	Name	I/O	Equivalent Circuit	Description
PX0/ \overline{SC}	Port X Serial clock	I/O	 <p>See Note 2) for the output circuit format. Schmitt inverter input</p>	Doubles as clock input/output pin for the serial interface and as bit "0" (input) of port X.
PY3/ \overline{EC}	Port Y Event count input	I	 <p>Schmitt inverter input</p>	Doubles as event counter (8 bits) input pin and as bit "3" (input) of port Y.
PY2/ \overline{WP}	Port Y Wake-up input	I		Doubles as wake-up input pin to reset the standby state and as bit "2" (input) of port Y.
PY1/ \overline{PWM}	Port Y PWM generator output	O	 <p>See Note 1) for the output circuit format.</p>	Doubles as PWM generator (14 bits) output pin and as bit "1" (output) of port Y.
PY0	Port Y	O		Output pin for bit "0" of port Y.
PA0 to PA3	Port A	I/O	 <p>See Note 2) for the output circuit format. Inverter input</p>	This 4-bit input/output port permits its each individual bit to be programmed to serve either as input or output. For the output format, a tri-state and pull-up resistor possible to be programmed, and it is also used as the standby resetting pin.
PB0/ $\overline{AD4}$ to PB3/ $\overline{AD7}$	Port B Analog voltage input	I/O		This 4-bit input/output port has the functions that are equivalent to those of port A. It is also used for A/D converter input.
PE0 to PE3	Port E	I/O		This 4-bit input/output port permits its each individual port to be programmed to serve either as input or output. For the output format, a tri-state and pull-up resistor possible to be programmed.
PF0 to PF3	Port F	I/O		This 4-bit input/output port has the functions that are equivalent to those of port E.
PI0/ $\overline{AD0}$ to PI3/ $\overline{AD3}$	Port I Analog voltage input	I/O		This 4-bit input/output port has the functions that are equivalent to those of port E. It is also used for A/D converter input.

Symbol	Name	I/O	Equivalent Circuit	Description
PD3/ SEG31 to PD0/ SEG28	Port D Segment output	O		Doubles as a 4-bit output port (For the output format, the inverter and pull-up resistor possible to be programmed.) and as the segment signal output pin for LCD.
PC3/ SEG27 to PC0/ SEG24	Port C Segment output	O	The transfer gate input signal is controlled based on 1/2, 1/3 bias methods in advance.	Doubles as a 4-bit output port (The output format is equivalent to port D.) and as the segment signal output pin for LCD.
PH3/ SEG23 to PH0/ SEG20	Port H Segment output	O		Doubles as a 4-bit output port (The output format is equivalent to port D.) and as the segment signal output pin for LCD. (Possible to designate in bit units.)
PG3/ SEG19 to PG0/ SEG16	Port G Segment output	O	See Note 3) for the output circuit format.	Doubles as a 4-bit output port (The output format is equivalent to port D.) and as the segment signal output pin for LCD.
SEG0 to SEG15	Segment output	O	 The transfer gate input signal is controlled based on 1/3 bias method in advance.	Segment signal output pin for LCD
COM0 to COM3	Common output	O	 Transfer gate output	Common signal output pin for LCD

Symbol	Name	I/O	Equivalent Circuit	Description
V _{LC1} to V _{LC3}	Power supply for LCD	—		Bias power supplying pin for LCD
V _L	Cut-off output	O		Control pin which cuts off the current input to the bias resistor for the external LCD during standby.
WP	Wake-up input	I	 Schmitt inverter input	It is the input pin to reset the standby mode, and reset by "1".
TEX	32kHz T/C clock input	I		Input pin for 32kHz timer clock generation circuit. Connect the 32.768kHz crystal oscillator between TEX and TX. When using as the event clock input, connect the clock oscillating source to TEX pin, open TX pin.
TX	32kHz T/C clock output	O		Output of clock generation circuit
V _{REF}	Reference voltage input	I		Reference voltage input for power supply voltage resetting circuit. Connect the zener diode normally.

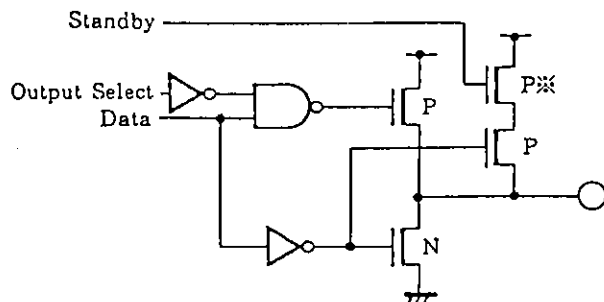
For all output ports, the output states of ports during standby possible to be programmed the state holding before standby or the change to the high impedance.

When the pull-up resistor is selected, it becomes a pulled-up state even it is input port.

During standby, it is impossible to change to the high impedance of PY0 and PY1 in the inverter output state. To change to the high impedance, select the pull-up resistor output, and then set to the high level output ("1" state).

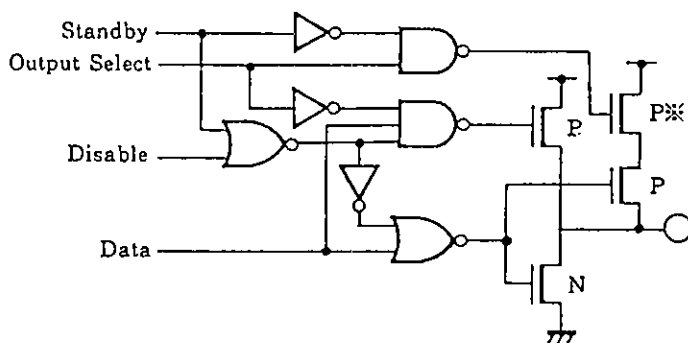
Note 1) Possible to select out of the following two ways for the output circuit format.
(port units : programmable)

- (a) Inverter output
- (b) Pull-up resistor output



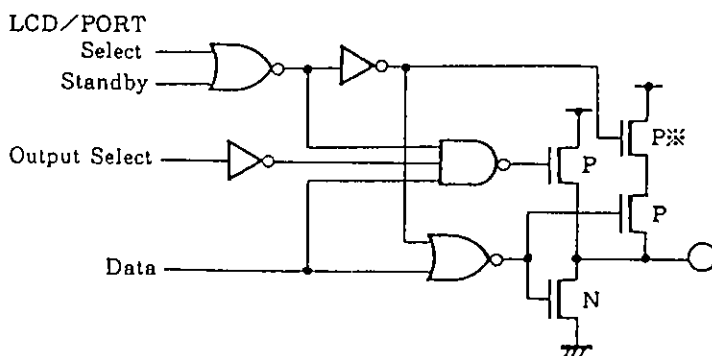
Note 2) Possible to select out of the following two ways for the output circuit format.
(port units : programmable)

- (a) Tri-state output
- (b) Pull-up resistor output



Note 3) Possible to select out of the following two ways for the output circuit format.
(port units : programmable)

- (a) Inverter output
- (b) Pull-up resistor output



※As the output pull-up resistor is CMOS pull-up output of about 10k Ω , the pull-up resistor becomes OFF state during "L" output.

Absolute Maximum Ratings

Ta = -20°C to +75°C, Vss = 0V

Item	Symbol	Rating	Unit	Remarks
Power supply voltage	V _{DD}	-0.3 to +7.0	V	
LCD bias voltage	V _{LC1} , V _{LC2} , V _{LC3}	-0.3 to +7.0*1	V	
Input voltage	V _{IN}	-0.3 to +7.0*1	V	
Output voltage	V _{OUT}	-0.3 to +7.0*1	V	
High level output current	I _{OH}	-5	mA	General purpose port*2: per pin
High level total output current	Σ I _{OH}	-50	mA	Entire pins total
Low level output current	I _{OL}	15	mA	General purpose port*2: per pin
	I _{OLC}	20	mA	High current port*3: per pin
Low level total output current	Σ I _{OL}	100	mA	Entire pins total
Operating temperature	T _{opr}	-20 to +75	°C	
Storage temperature	T _{stg}	-55 to +150	°C	
Allowable power dissipation	P _D	600	mW	

Note) Usage exceeding absolute maximum ratings may permanently impair the LSI. Normal operation should better take place under the recommended operation conditions. Exceeding those conditions may adversely affect the reliability of the LSI.

*1) V_{LC1}, V_{LC2}, V_{LC3}, V_{IN} and V_{OUT} should not exceed V_{DD} + 0.3V.

*2) Specifies the output current of the general purpose I/O port PA to PI, SO, \overline{SC} , PY0 and PY1.

*3) The high current operation transistors are the N-CH transistors of the PC and PD ports.

Recommended Operating Condition

Vss = 0V

Item	Symbol	Min.	Max.	Unit	Remarks
Power supply voltage	V _{DD}	4.5	5.5	V	Guaranteed range of operation by EXTAL clock
		2.5	5.5	V	Guaranteed range of operation by TEX clock, guaranteed range of data hold during STOP.
LCD bias voltage	V _{LC1} , V _{LC2} , V _{LC3}	V _{SS}	V _{DD}	V	Liquid crystal power supply range*1
High level input voltage	V _{IH}	0.7V _{DD}	V _{DD}	V	
	V _{IHS}	0.8V _{DD}	V _{DD}	V	Hysteresis input*2
	V _{IHEX}	V _{DD} -0.4	V _{DD} +0.3	V	EXTAL pin*3
Low level input voltage	V _{IL}	0	0.3V _{DD}	V	
	V _{ILS}	0	0.2V _{DD}	V	Hysteresis input*2
	V _{ILEX}	-0.3	0.4	V	EXTAL pin*3
Operating temperature	T _{opr}	-20	+75	°C	

*1) The optimum value is determined by the characteristics of the liquid crystal display element used.

*2) The TEX pin when the counter mode is selected by each of INT, RMC, PX0, PX2, PY2, PY3, \overline{RST} pins and mask option.

*3) Specified only during external clock input.

Electrical Characteristics

DC characteristics

Ta = -20°C to +75°C, Vss = 0V

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
High level output voltage	VOH	PA to PI* ¹ PX0, PX1 PY0, PY1 VL (VOL only) RST (VOL only) PC* ¹ , PD* ¹	VDD = 4.5V, IOH = -0.5mA* ²	4.0			V
			VDD = 4.5V, IOH = -1.0mA* ²	3.5			V
			VDD = 4.5V, IOH = -10 µA* ³	4.0			V
			VDD = 4.5V, IOH = -200 µA* ³	2.4			V
Low level output voltage	VOL		VDD = 4.5V, IOL = 1.8mA			0.4	V
			VDD = 4.5V, IOL = 3.6mA			0.6	V
			VDD = 4.5V, IOL = 12mA			1.5	V
Input current	IiHE	EXTAL	VDD = 5.5V, VIH = 5.5V	0.5		40	µA
	IiLE		VDD = 5.5V, VIL = 0.4V	-0.5		-40	µA
	IiHT	TEX* ⁴	VDD = 5.5V, VIH = 5.5V	0.1		10	µA
	IiLT			-0.1		-10	µA
	IiLR	RST* ⁵	VDD = 5.5V, VIL = 0.4V	-1.5		-400	µA
	IiL	PA* ⁶ , PB* ⁶ , PE* ⁶ , PF* ⁶ , PI* ⁶ , PX0* ⁶ , PX1* ⁶ , PX2* ⁸ , PY0* ⁷ , PY1* ⁷ , PY2* ⁸ , PY3* ⁸ , INT* ⁸ , RMC* ⁸ , RST* ⁵ , TEX* ⁴				±10	µA
High impedance I/O leakage current	IIZ		VDD = 5.5V			±10	µA
Common output impedance	Rcom	COM0 to COM3	VDD = 5V VLC1 = 3.75V		3	5	kΩ
Segment output impedance	Rseg	SEG0 to SEG15 SEG16 to SEG31* ¹	VLC2 = 2.5V VLC3 = 1.25V		5	15	kΩ
Supply current* ⁹	IDD1	VDD	Entire output pins open				
			Crystal oscillation (C1 = C2 = 27pF) of VDD = 5.5V, 4.19MHz		7	20	mA
			Crystal oscillation (C1 = C2 = 47pF) of VDD = 3V, 32kHz		50	250	µA
			SLEEP mode				
			VDD = 5.5V, 4.19MHz oscillation		5	12	mA
			VDD = 3V, 32kHz oscillation		40	200	µA
			STOP mode				
	IDDSP1		VDD = 3V, 32kHz with T/C		7	40	µA
			VDD = 5.5V, 32kHz without T/C (For mask option select counter, Pin is fixed.)			10	µA
	IDDSP2						
	IDDS1						
	IDDS2						
Input capacity	CIN	Other than VLC1 to VLC3, COM0 to COM3, SEG0 to SEG15, SEG16 to SEG31* ¹ , Vss, VDD pins	Clock 1MHz 0V other than the measured pins		10	20	pF

- *1) The PC, PD, PG and PH show when the combined pins are selected as the port, and SEG16 to SEG31 show when the combined pins are selected as the segment output.
- *2) It is when the respective pins of PA to PI, PX0 and PX1 select the tri-state output circuit, and PY0 and PY1 are when the inverter output circuit is selected.
- *3) It is when the respective pins of PA to PI, PX0, PX1, PY0 and PY1 select the pull-up resistor.
- *4) The TEX pin specifies the input current when the crystal oscillation is selected by the mask option, and specifies the leakage current when the schmitt input is selected.
- *5) The RST pin specifies the input current when the pull-up resistor is selected, and specifies leakage current when non-resistor is selected.
- *6) The respective pins of PA, PB, PE, PF, PI, PX0 and PX1 specify the input current when the pull-up resistor is selected, and specify the leakage current when the port state during using the tri-state output circuit or standby is selected at high impedance.
- *7) The respective pins of PY0 and PY1 specify the input current when the pull-up resistor is selected, and specify the leakage current when in the port state during standby is selected at high impedance.
- *8) The respective pins of PX2, PY2, PY3, INT and RMC only specify the leakage current.
- *9) However, except for EPROM power supply current.

AC Characteristics

(1) Clock timing

$T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$, $V_{DD} = 4.5\text{V}$ to 5.5V , $V_{SS} = 0\text{V}$

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
System clock frequency	f_c	XTAL EXTAL	Fig. 1, Fig. 2	1		5	MHz
System clock input pulse width	t_{xL} t_{xH}	EXTAL	Fig. 1, Fig. 2 (External clock drive)	90			ns
System clock input rising and falling times	t_{cR} t_{cF}					200	ns
System clock frequency	f_{cs}	TEX* ² TX	$V_{DD} = 2.5$ to 5.5V Fig. 2		32.768		kHz
Event count clock input pulse width	t_{eL} t_{eH}	\overline{EC}	Fig. 3	t_{sys} * ¹ $+0.05$			μs
Event count clock input rising and falling times	t_{eR} t_{eF}	\overline{EC}	Fig. 3			20	ms
Event count input clock input pulse width	t_{tL} t_{tH}	TEX* ³	Fig. 3	10			μs
Event count input clock rising and falling times	t_{tR} t_{tF}	TEX* ³	Fig. 3			20	ms

- *1) t_{sys} in the EXTAL input clock is $8/f_c$
 t_{sys} in the TEX input clock is $4/f_{cs}$

*2) Specified when the crystal oscillation mode is selected by the mask option.

*3) Specified when the counter mode is selected by the mask option.

Note) When adjusting the frequency accurately, there may be cases in which they may differ from Fig. 2.

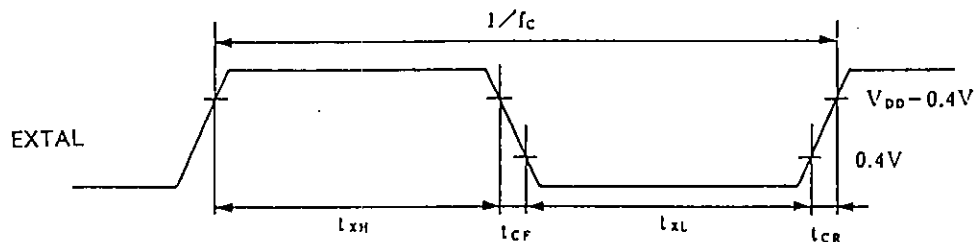


Fig. 1 Clock timing

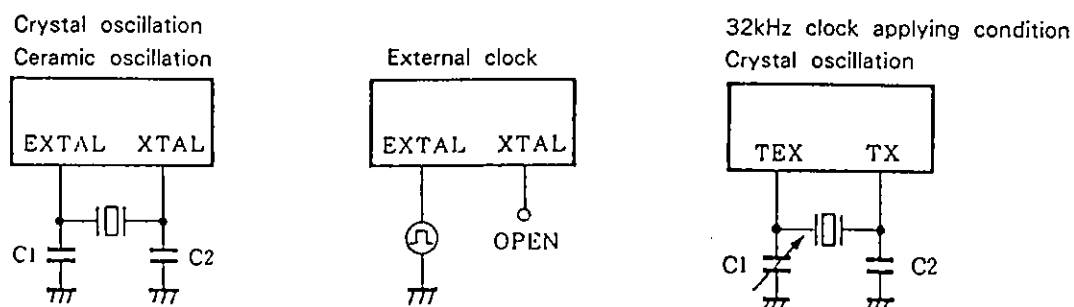


Fig. 2 Clock applying condition

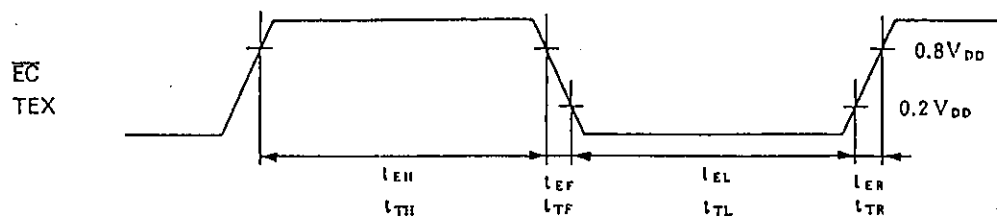


Fig. 3 Event count clock timing

(2) Serial transfer

 $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$, $V_{DD} = 4.5\text{V}$ to 5.5V , $V_{SS} = 0\text{V}$

Item	Symbol	Pin	Condition	Min.	Max.	Unit
Serial transfer clock ($\overline{\text{SC}}$) cycle time	tkcy	$\overline{\text{SC}}$	Input mode	$t_{\text{sys}}/4 + 1.42$		μs
			Output mode	$2t_{\text{sys}}$		μs
Serial transfer clock ($\overline{\text{SC}}$) high and low level widths	tkH tkL	$\overline{\text{SC}}$	Input mode	$t_{\text{sys}}/8 + 0.7$		μs
			Output mode* ¹	$t_{\text{sys}} - 0.1$		μs
			Output mode* ²	$t_{\text{sys}} - 1.6$		μs
Serial data input setup time (against $\overline{\text{SC}}$ \uparrow)	tsik	SI	$\overline{\text{SC}}$ input mode	0.1		μs
			$\overline{\text{SC}}$ output mode	0.2		μs
Serial data input hold time (against $\overline{\text{SC}}$ \uparrow)	tkSI	SI	$\overline{\text{SC}}$ input mode	$t_{\text{sys}}/8 + 0.5$		μs
			$\overline{\text{SC}}$ output mode	0.1		μs
High data delay time from $\overline{\text{SC}}$ falling* ³	tkSO	SO			$t_{\text{sys}}/8 + 0.5$	μs
High data delay time from $\overline{\text{SC}}$ falling* ⁴	tkSO	SO			$t_{\text{sys}}/8 + 1.6$	μs
Low data delay time from $\overline{\text{SC}}$ falling	tkSO	SO			$t_{\text{sys}}/8 + 0.5$	μs

Note 1) t_{sys} in the EXTAL input clock is $8/f_c$. (It is impossible to use in TEX input clock.)

2) The Load of data output delay is $50\text{pF} + 1\text{TTL}$

*1) It is specified when $\text{PX0}/\overline{\text{SC}}$ pin is selected to the tri-state output by the program.

*2) It is specified when $\text{PX0}/\overline{\text{SC}}$ pin is selected to the pull-up resistance by the program.

As the t_{sys} receives restriction by this item, take notice that it limits the upper limit of the system clock frequency f_c .

*3) This item is specified when $\text{PX1}/\text{SO}$ pin is selected to the tri-state output by the program.

*4) This item is specified when $\text{PX1}/\text{SO}$ pin is selected to the pull-up resistance by the program.

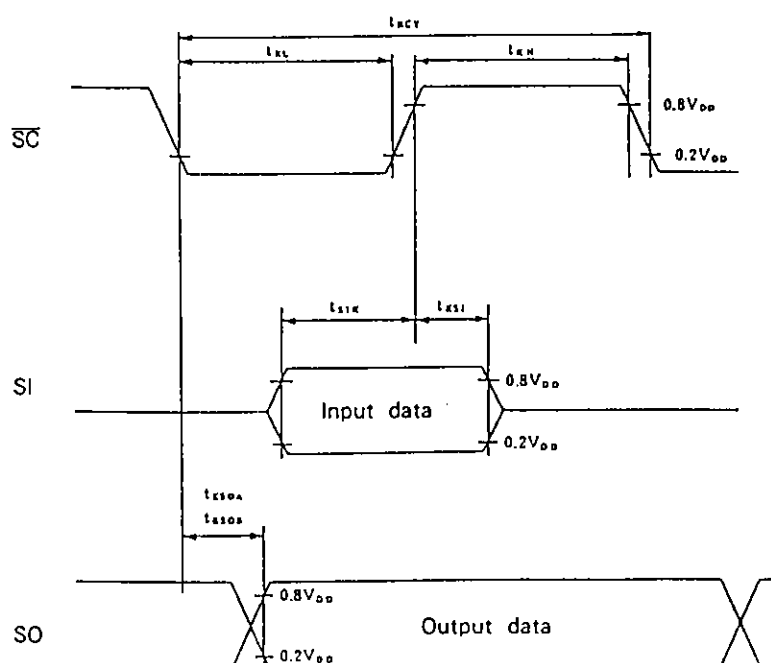


Fig. 4 Serial transfer timing

(3) A/D converter

 $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$, $V_{SS} = 0\text{V}$

Analog input voltage	Pin	Condition	Digital conversion value
0.0 to 0.33V	AD0 to AD7	$V_{DD} = 5\text{V}$	000
0.82 to 1.29V			001
1.78 to 2.21V			010
2.69 to 3.06V			011
3.56 to 4.06V			100
4.62 to 5.0V			101

Note) The digital conversion value are the values when AB_H address of the RAM file 1 in the program are read.

(4) Power Supply Voltage Detection Reset Function

 $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$, $V_{SS} = 0\text{V}$

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
Power supply voltage detection reset function of operation voltage range	V_{LPOP}	V_{DD}	Voltage range allowing system operation (32kHz system operation below $V_{DD} = 4.5\text{V}$)	2.5		5.5	V
Power supply voltage drop detection function	V_{POP}	V_{DD}	When V_{REF} pin voltage is 3.3V Flag set when voltage drops System reset when voltage rises	3.8	4.0	4.2	V

The graph in Fig. 5 shows the relationship between the power supply voltage V_{DD} and reference voltage V_{REF} of the power supply voltage detection reset function.

Note) The graph in Fig. 5 serves as guide to the function operation area obtained using average devices.
Individual adjustment is needed when Zener diodes, etc., are connected to the V_{REF} pin.

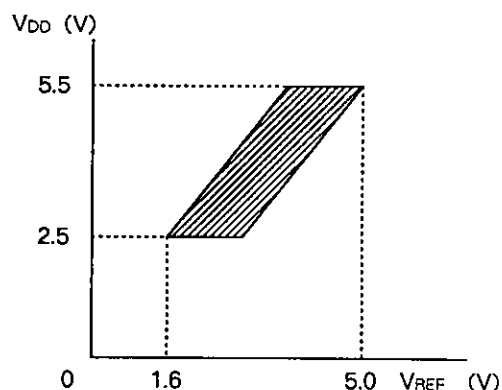


Fig. 5 Power supply voltage detection reset function chart

(5) Others

 $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$, $V_{DD} = 4.5\text{V}$ to 5.5V , $V_{SS} = 0\text{V}$

Item	Symbol	Pin	Condition	Min.	Max.	Unit
External interruption high and low level widths	t_{11H}, t_{11L}	INT	During edge detection mode	$t_{\text{sys}} + 0.05$		μs
Reset input low level width	t_{RSL}	RST		$2t_{\text{sys}}^{*1}$		μs
Wake-up input high level width	t_{WPH}	WP	STOP mode	500		ns
			SLEEP mode	$t_{\text{sys}} + 0.05$		μs
Wake-up input low level width	t_{WPL}	PA0 to PA3	STOP mode	500		ns
			SLEEP mode	$t_{\text{sys}} + 0.05$		μs

Note) t_{sys} in the EXTAL input clock is $8/f_c$ t_{sys} in the TEX input clock is $4/f_c$

*1) For resetting when operating in TEX input clock, hold the low level more than the oscillation stabilizing time of EXTAL input clock.

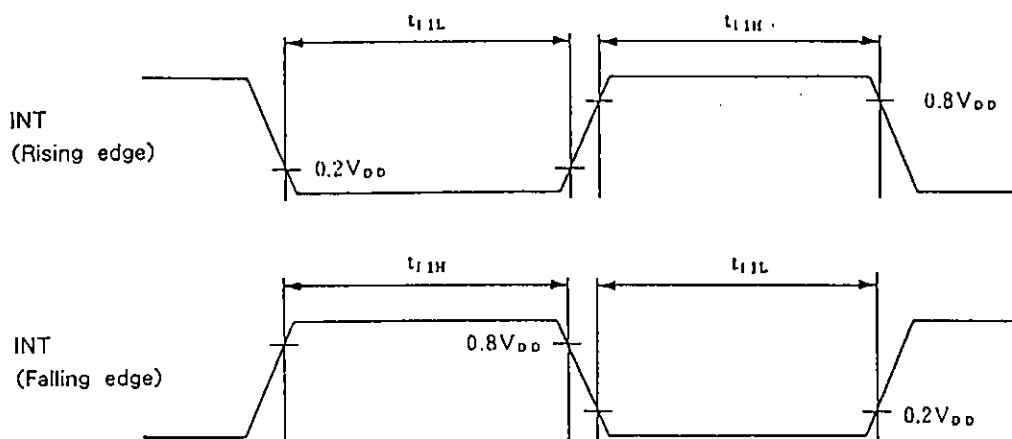


Fig. 6 Interruption input timing

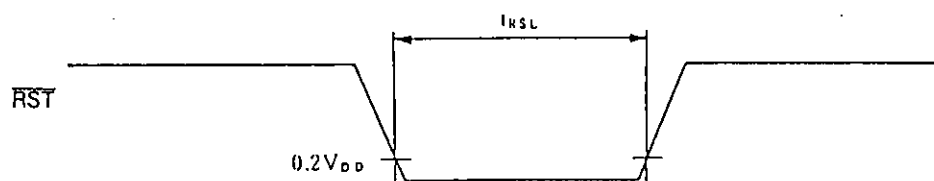


Fig. 7 Reset input timing

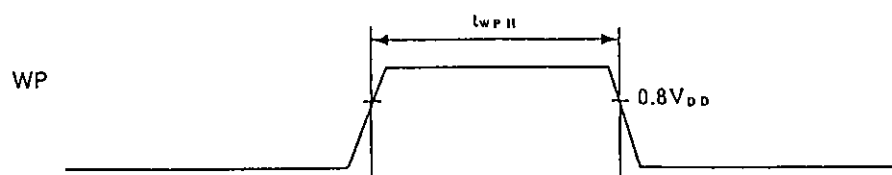


Fig. 8 Wake-up input timing

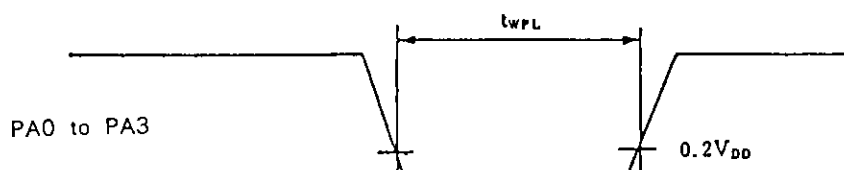


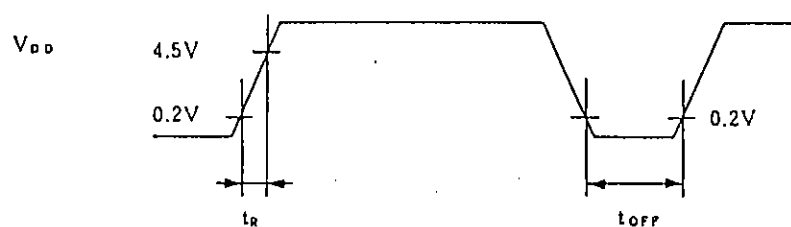
Fig. 9 Wake-up input timing

Power on reset *

 $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$, $V_{SS} = 0\text{V}$

Item	Symbol	Pin	Condition	Min.	Max.	Unit
Power supply rising time	t_R	V_{DD}	Power on reset	0.05	50	ms
Power supply cut-off time	t_{OFF}		Repetitive power on reset	1		ms

* Specifies only when power on reset function is selected.



The power supply should rise smoothly.

Fig. 10 Power on reset

Notes on Application

See Fig. 11, Additive capacity calculation chart, when using the crystal oscillator and select the appropriate capacity.

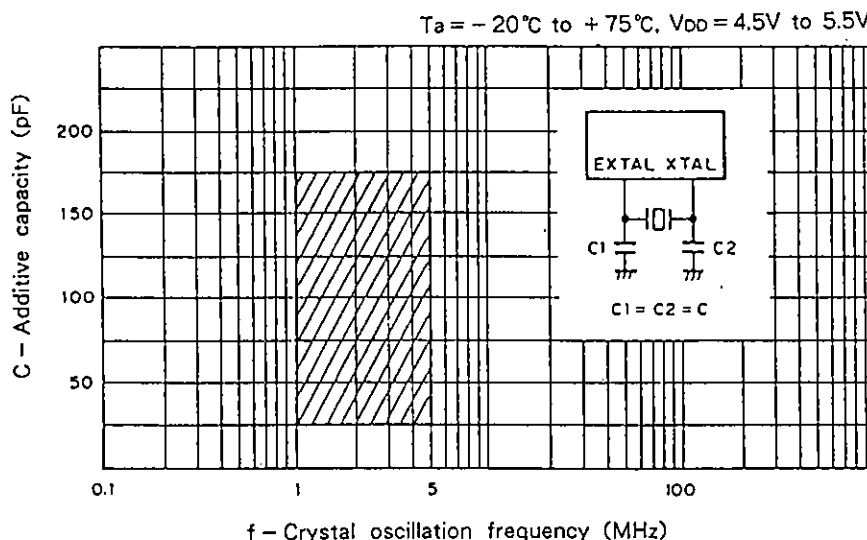


Fig. 11 Crystal oscillation circuit additive capacity calculation chart

Note) The above chart shows a range in which the average quartz resonator has a relatively fast oscillation rising edge and stable characteristics. The capacity should be selected to correspond to the appropriate constant for each quartz resonator, should the frequency of the quartz resonator be accurately adjusted,

Fig. 12 shows an example of a circuit which can accurately adjust the frequency. Used here a crystal with 12pF equivalent (C_L).

Although C_1 and C_2 become out of the recommended range in this case, such a crystal oscillator can be used.

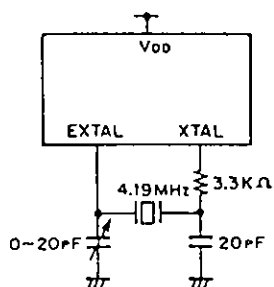


Fig. 12 Frequency adjustment circuit

When using the A/D converter as the key input, it is recommended that the circuit structure shown in Fig. 13 be used.

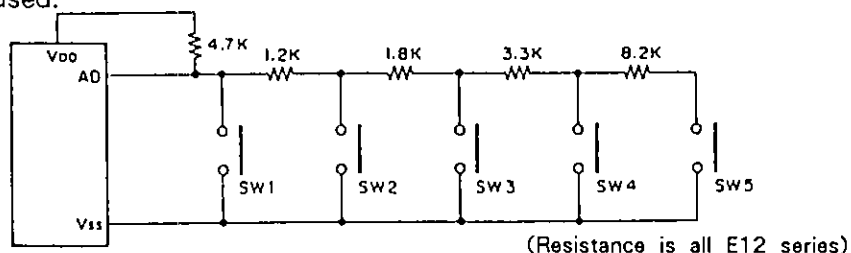


Fig. 13 Recommended example of key circuit by A/D converter

EPROM read timing

 $T_a = -20^{\circ}\text{C}$ to $+75^{\circ}\text{C}$, $V_{DD} = 4.5$ to 5.5V , $V_{SS} = 0\text{V}$

Item	Symbol	Pin	Min.	Max.	Unit
Address→data input delay time	t_{ACC}	A0 to A12, I0 to I7		300	ns
Address→input holding time	t_{IH}	A0 to A12, I0 to I7	0		ns

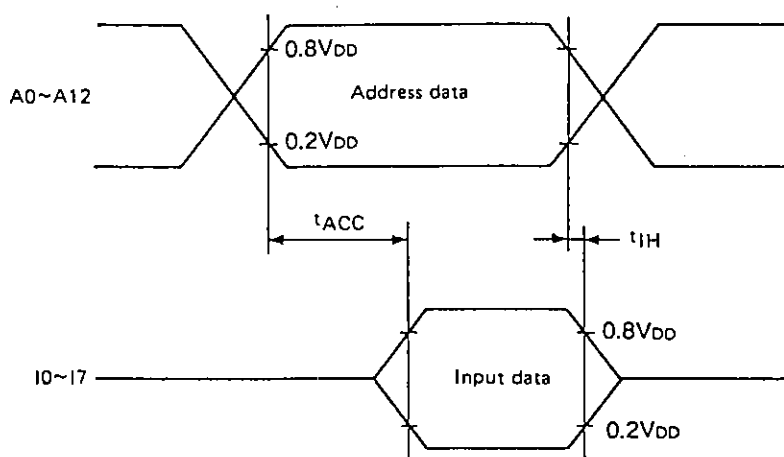


Fig. 14 EPROM timing

Products List

Optional item	Mass product	CXP5070HU01AQ
Package	80-pin plastics QFP	80-pin ceramic QFP
ROM capacity	8K-byte/6K-byte	EPROM 8K-byte
Pull-up resistance of reset pin	Existent/non-existent	Existent
Incorporated power on reset circuit	Existent/non-existent	Existent
32kHz timer/counter	Timer/Counter	Timer mode

Note) All the piggyback/evaluator is combined chips.

For EVA CAP other than EVA CAP-2, execute the piggyback/EVA switching through the PESEL pin of PIN 43.

Usage Instruction

CXP5070's piggyback/EVA switching is executed as shown in the diagram. Particular care is needed as reverse plugging is required.

